

## Patent Abstracts of Japan

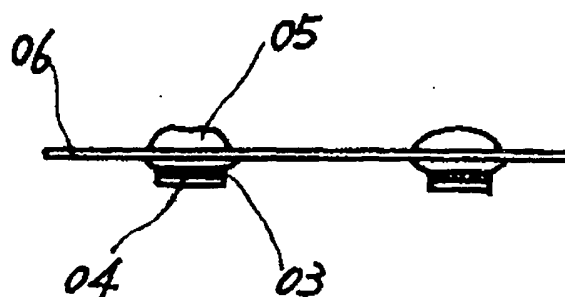
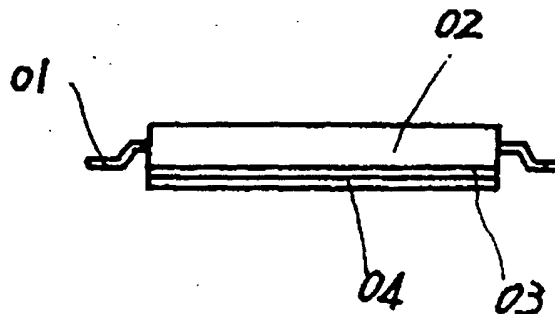
PUBLICATION NUMBER : 57068053  
 PUBLICATION DATE : 26-04-82  
 APPLICATION DATE : 16-10-80  
 APPLICATION NUMBER : 55144828

APPLICANT : SEIKO EPSON CORP;

INVENTOR : KATO JUNICHI;

INT.CL. : H01L 23/00 H01L 23/02 H01L 23/32

TITLE : INTEGRATED CIRCUIT PACKAGE



ABSTRACT : PURPOSE: To facilitate the mounting work of an integrated circuit on a substrate by forming an adhesive bond or the like layer on the front or back surface of an integrated circuit package and covering the adhesive exposed surface with a protective film having adhesion preventing effect.

CONSTITUTION: An adhesive substance layer 03 made of thermoplastic adhesive or adhesive, e.g., acryl or the like and its protective film 04 are formed on one flat surface of a molded IC 02 of, for example, flat package type. In a film carrier type package, for example, an adhesive layer 03 and a protective film 04 are similarly formed on the surface contacted with the mounting substrate of an IC 05 formed on a flexible tape 06. In mounting on the substrate, the film 04 is removed, the ICs 02, 05 are bonded to the substrate, and lead terminal is soldered thereto. In this manner, it can simplify the mounting work inexpensively and can prevent the displacement of the mounting position.

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PUBLICATION NUMBER : 04352491  
PUBLICATION DATE : 07-12-92

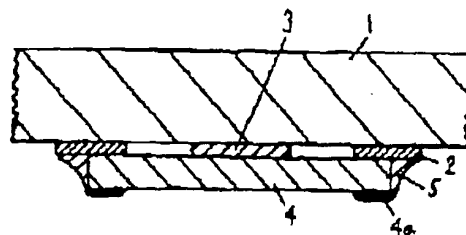
APPLICATION DATE : 30-05-91  
APPLICATION NUMBER : 03127465

APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

INVENTOR : UMIBE SUSUMU;

INT.CL. : H05K 3/34

TITLE : METHOD OF PACKAGING  
ELECTRONIC PARTS



**ABSTRACT :** **PURPOSE:** To enable a working property to be improved and a packaging accuracy to be improved in self-alignment effect by using a hot-melt resin instead of a thermosetting resin as an adhesive.

**CONSTITUTION:** A heat-resistance type not melt adhesive 3 which is heated to approximately 220°C is coated by an exclusive application machine between electrode 2 of a substrate which is formed on a surface of a glass-epoxy resin printed-wiring board 1, then electronic parts 4 are placed on it, and then they are cooled and the substrate 1 and electronic parts 4 are adhered. After this, flux is coated on a surface of an electrode 4a of the electronic parts 4 and that of the electrode 2 of the substrate 1, the substrate is dipped into a solder bath where an eutectic solder at approximately 250°C is filled, and then the electrode 2 of the substrate 1 and the electrode 4a of the electronic parts 4 are connected by a solder 5. When removing the electronic parts 4, heat is applied to them from an outside for remelting the solder 5 and then viscosity of the adhesive 3 is reduced, thus achieving removal mechanically. Use of the heat-resistance hot-melt adhesive allows viscosity to be reduced for easy removal by applying heat at the time of removal.

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